

ABSTRACT OF THE DISCLOSURE

Provided is a hybrid integrated circuit device which can more effectively stabilize a circuit configured to operate at a high speed. A hybrid integrated circuit device of the embodiment includes a metal substrate provided with an insulating layer on a surface thereof, a conductive pattern formed on a surface of the insulating layer, a semiconductor element fixed onto the conductive pattern, a lead as external connecting means fixed to the conductive pattern in the periphery of the metal substrate, and a contact portion for electrically connecting the conductive pattern electrically connected to the semiconductor element to the metal substrate in the vicinity of the semiconductor element.